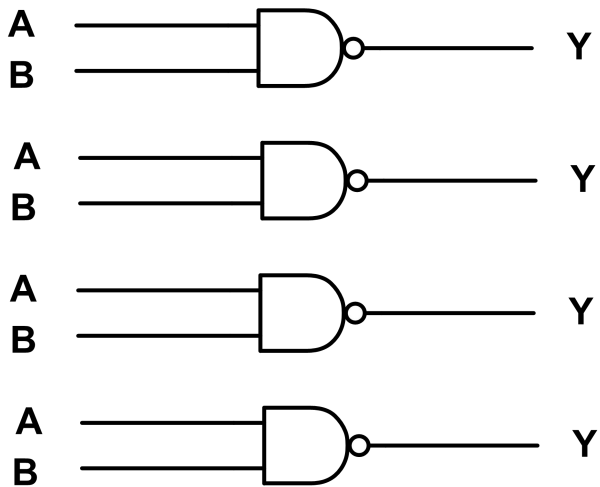


GT74LVC00

Quadruple 2-Input Positive-NAND Gate

1 Features	2 Application
<ul style="list-style-type: none"> - Supports 5V V_{CC} operation - Inputs accept voltages to 5.5 V - Provides down translation to V_{CC} - Low power consumption, 10-μA Max I_{CC} - ± 24-mA output drive at 3.3 V - I_{off} supports live insertion, partial-power-down mode, and back drive protection 	<ul style="list-style-type: none"> - AV receivers - Audio docks: portable - Blu-ray players and home theater - MP3 players or recorders - Personal digital assistants (PDAs) - Solid state drives (SSDs): client and enterprise - TVs: LCD, digital, and high-definition (HDTV) - Tablets: enterprise - Video analytics: server - Wireless headsets, keyboards, and mice

3 Description	Circuit Diagram
<p>GT74LVC00 quadruple 2-input positive-NAND gate is designed for 1.65-V to 5.5-V V_{CC} operation.</p> <p>The GT74LVC00 device performs the Boolean function $Y = \overline{A \times B}$ or $Y = \overline{A} + \overline{B}$. in positive logic.</p> <p>Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these device as translators in a mixed 3.3-V/5-V system environment.</p>	

4 Revision History

Revision	Date	Note
Rev. A1.0	2023. 10. 23	Original Version
Rev.A1.1	2023. 10. 23	1.Updated Package Qty 2.Added Tape and Reel Information 3. Added Application Note
Rev.A1.2	2023. 12. 26	1. Added Marking 2. Added MSL
Rev.A1.3	2024. 01. 26	Updated Part Name

The latest datasheet version should be checked on the GTIC official website, as the company does not actively inform customers about updates to the datasheet.

5 Device Summary, Pin and Packages

Table 5-1. Device Summary⁽¹⁾

Serial Name	Part Name	Package	Body Size (Nom)	Marking ⁽²⁾⁽⁴⁾	MSL ⁽³⁾	Package Qty
GT74LVC00	GT74LVC00PD	SOP-14(SOIC-14)	8.65mm×3.90mm×1.75mm	GT74LVC00 XXXXXXX	3	Tape and Reel,4000
	GT74LVC00TD	TSSOP-14	5.00mm×4.40mm×1.20mm	GT74LVC00 XXXXXXX	3	Tape and Reel,4000

(1) For all available packages, please contact product sales

(2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

(3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.

(4) "XXXXX" in Marking will be appeared as the batch code.

FAE: 13148878879

5 Device Summary, Pin and Packages(continued)

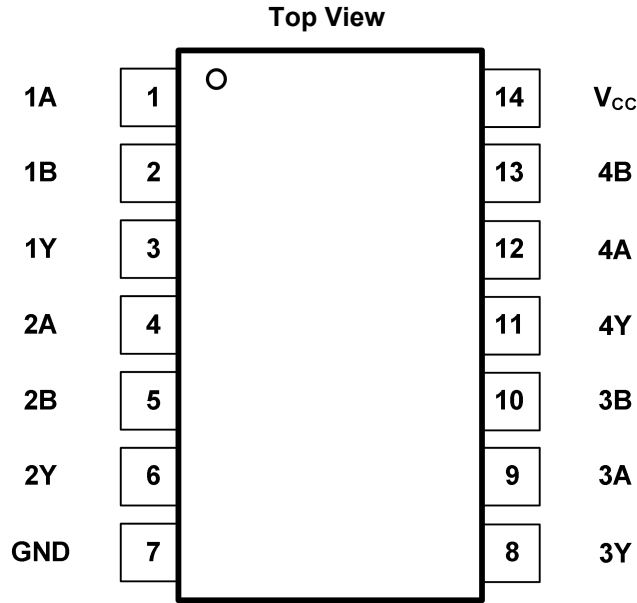


Fig.5-1. GT74LVC00: PD (SOP14/SOIC-14) Package

GT74LVC00: TD (TSSOP14) Package

Table 5-1 Pin Definition

Pin		Type	Description
Name	PD TD		
1A	1	I	A input for gate 1
1B	2	I	B input for gate 1
1Y	3	O	Output for gate 1
2A	4	I	A input for gate 2
2B	5	I	B input for gate 2
2Y	6	O	Output for gate 2
GND	7	-	Ground
3Y	8	O	Output for gate 3
3A	9	I	A input for gate 3
3B	10	I	B input for gate 3
4Y	11	O	Output for gate 4
4A	12	I	A input for gate 4
4B	13	I	B input for gate 4
VCC	14	-	Power input

6 Voltage, Temperature, ESD and Thermal Ratings

6.1 Absolute Maximum Ratings⁽¹⁾

Parameters		Min	Max	Unit
V _{CC}	Supply voltage range	-0.5	6.5	V
V _I	Input voltage range	-0.5	6.5	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
V _O	Voltage range applied to any output in the high or low state ⁽²⁾	-0.5	V _{CC} +0.5	V
I _{IK}	Input clamp current	V _I <0	-50	mA
I _{OK}	Output clamp current	V _O <0	-50	mA
I _O	Continuous output current		±50	mA
	Continuous current through V _{CC} or GND		±100	mA
T _J	Junction temperature under bias		150	°C
T _{stg}	Storage temperature range	-55	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability..

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

ESD		Value	Unit
V(ESD)	Electrostatic Discharge	Human-Body Model (HBM) ⁽¹⁾	8 K
		Charged-device model (CDM) ⁽²⁾	2 K

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6 Voltage, Temperature, ESD and Thermal Ratings(continued)

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	1.65	5.5	V
V _{IH}	High-Level Input Voltage	VCC=1.65V to 1.95V	0.65×VCC	V
		VCC=2.3V to 2.7V	1.7	
		VCC=3V to 3.6V	2	
		VCC=4.5V to 5.5V	0.7×VCC	
V _{IL}	Low-Level Input Voltage	VCC=1.65V to 1.95V	0.35×VCC	V
		VCC=2.3V to 2.7V	0.7	
		VCC=3V to 3.6V	0.8	
		VCC=4.5V to 5.5V	0.3×VCC	
V _I	Input Voltage	0	5.5	V
V _O	Output Voltage	0	VCC	V
I _{OH}	High-Level Output Current	VCC=1.65V	-4	mA
		VCC=2.3V	-8	
		VCC=3V	-16	
		VCC=4.5V	-24	
I _{OL}	Low-Level Output Current	VCC=1.65V	4	mA
		VCC=2.3V	8	
		VCC=3V	16	
		VCC=4.5V	24	
Δt/Δv	Input Transition Rise or Fall Rate	VCC=1.8V±0.15V, 2.5V±0.2V	20	ns/V
		VCC=3.3V±0.3V	10	
		VCC=5V±0.5V	5	
TA	Operating Free-Air Temperature	-40	125	°C

6.4 Thermal Information

Package Type	θ _{JA}	θ _{JC}	Unit
TSSOP-14	180	35	°C/W
SOP-14(SOIC-14)	120	36	°C/W

7 Electrical Specifications⁽¹⁾

Over recommended operating free-air temperature range (unless otherwise noted)

Parameter	Test Conditions	V _{CC}	-40°C to 85°C			-40°C to 125°C			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{OH}	I _{OH} =-100 μA	1.65 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			V
	I _{OH} =-4 mA	1.65 V	1.2			1.2			
	I _{OH} =-8 mA	2.3 V	1.9			1.9			
	I _{OH} =-16 mA	3 V	2.4			2.4			
	I _{OH} =-24 mA		2.3			2.3			
	I _{OH} =-32 mA	4.5 V	3.8			3.8			
V _{OL}	I _{OL} =100 μA	1.65 V to 5.5 V			0.1			0.1	V
	I _{OL} =4 mA	1.65 V			0.45			0.45	
	I _{OL} =8 mA	2.3 V			0.3			0.3	
	I _{OL} =16 mA	3 V			0.4			0.4	
	I _{OL} =24 mA				0.55			0.55	
	I _{OL} =32 mA	4.5 V			0.55			0.55	
I _I	A or B Inputs	V _I =5.5 V or GND	0 to 5.5 V		±5			±5	μA
I _{off}		V _I or V _O =5.5 V	0		±10			±10	μA
I _{CC}		V _I =5.5 V or GND, I _O =0	1.65 V to 5.5 V		10			10	μA
ΔI _{CC}		One Input at V _{CC} - 0.6 V, Other Inputs at V _{CC} or GND	3 V to 5.5 V		500			500	μA
C _i		V _I =V _{CC} or GND	3.3 V		5			5	pF

(1) All unused digital inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

7 Electrical Specifications (continued)

Over recommended operating free-air temperature range, CL=30 pF or 50 pF (unless otherwise noted)

Parameter	From (Input)	To (Output)	-40°C to 85°C								Unit
			V _{CC} =1.8 V ± 0.15 V		V _{CC} =2.5 V ± 0.2 V		V _{CC} =3.3 V ± 0.3 V		V _{CC} =5 V ± 0.5 V		
			Min	Max	Min	Max	Min	Max	Min	Max	
tpd	A or B	Y	1	9.8	1	6.9	1	4.8	1	4.1	ns

Over recommended operating free-air temperature range, CL=30 pF or 50 pF (unless otherwise noted)

Parameter	From (Input)	To (Output)	-40°C to 125°C								Unit
			V _{CC} =1.8 V ± 0.15 V		V _{CC} =2.5 V ± 0.2 V		V _{CC} =3.3 V ± 0.3 V		V _{CC} =5 V ± 0.5 V		
			Min	Max	Min	Max	Min	Max	Min	Max	
tpd	A or B	Y	1	11.3	1	9	1	6	1	5.5	ns

Operating Characteristics

T_A=25°C

	Parameter	Test Conditions	V _{CC} =1.8 V	V _{CC} =2.5 V	V _{CC} =3.3 V	V _{CC} =5 V	Unit
			Typ	Typ	Typ	Typ	
Cpd	Power Dissipation Capacitance	f=10 MHz	18	18	23	26	pF

8 Typical Characteristics

Over recommended operating free-air temperature range, CL=30 pF or 50 pF (unless otherwise noted)

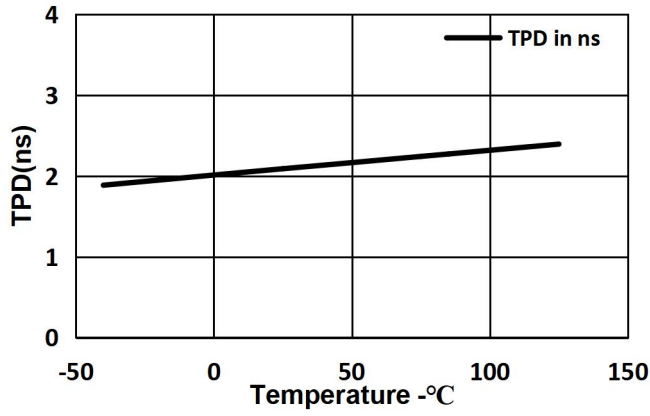


Fig.8-1. T_{PD} Across Temperature at 3.3 V V_{CC}

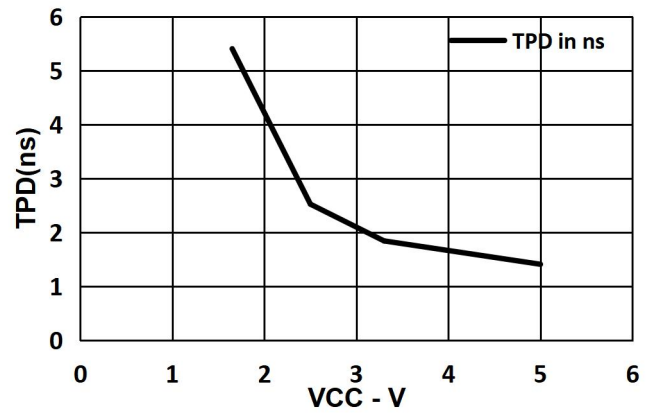
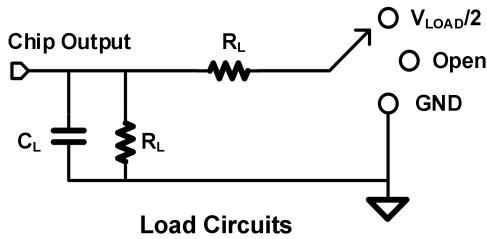


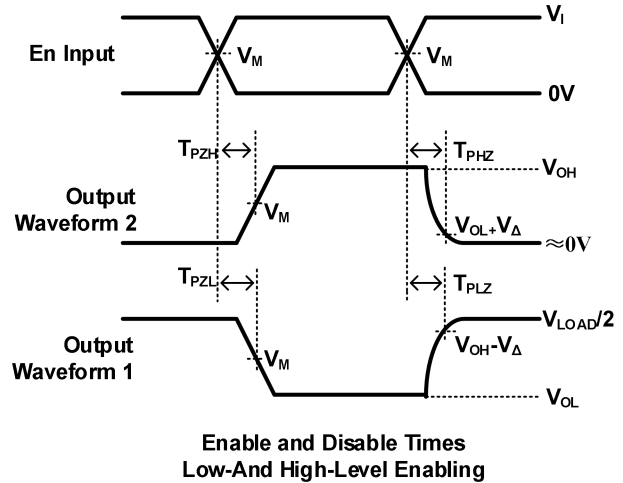
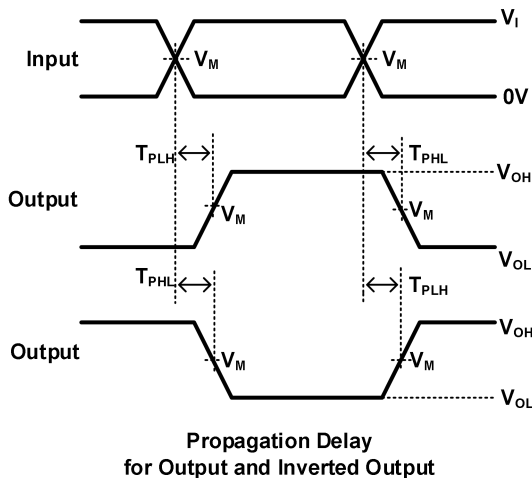
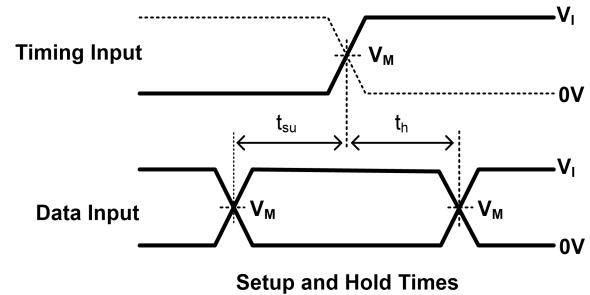
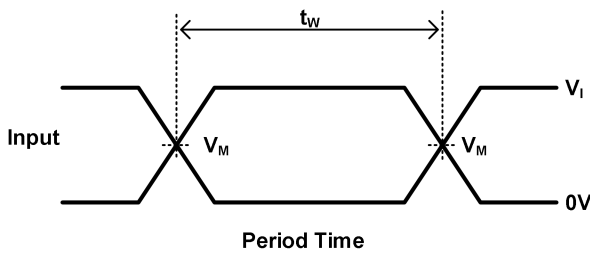
Fig.8-2. T_{PD} Across V_{CC} at 25°C

9 Parameter Measurement Information



TEST	S1
T_{PHL}/T_{PLH}	OPEN
T_{PLZ}/T_{PZL}	V_{LOAD}
T_{PHZ}/T_{PZH}	GND

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_i	T_r/T_f					
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1k Ω	0.15V
$2.5V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 Ω	0.15V
$3.3V \pm 0.15V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500 Ω	0.3V
$5V \pm 0.15V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500 Ω	0.3V



Notes: A. C includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, Z=50.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en} .

G. t_{PLH} and t_{PHL} are the same as t_{pd} .

H. All parameters and waveforms are not applicable to all device.

10 Detailed Description

10.1 Overview

The GT74LVC00 device contains four 2-input positive-NAND gates and performs the Boolean function $Y = \overline{A \times B}$ or $Y = \overline{A} + \overline{B}$ on each gate. This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

10.2 Functional Block Diagram

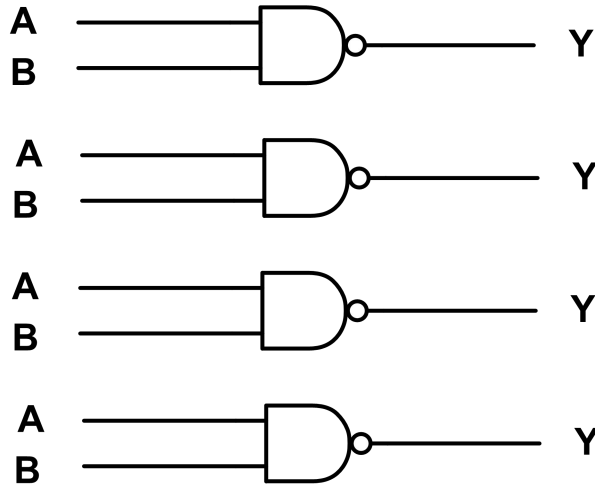


Fig.10-1.Functional Block Diagram

10.3 Feature Description

- Wide operating voltage range.
- Operates from 1.65 V to 5.5 V.
- Allows down voltage translation.
- Inputs accept voltages to 5.5 V.
- I_{off} feature allows voltages on the inputs and outputs, when V_{CC} is 0 V.

10.4 Device Functional Modes

Input A		Output Y
A	B	Y
H	H	L
L	X	H
X	L	H

11 Application Note

11.1 Application Information

GT74LVC00 is a high-drive CMOS device that can be used for a multitude of buffer-type functions. It can produce 24 mA of drive current at 3.3 V. Therefore, this device is ideal for driving multiple inputs and for high-speed applications up to 100 MHz. The inputs and outputs are 5.5-V tolerant allowing the device to translate up to 5.5 V or down to V_{CC} .

11.2 Typical Application

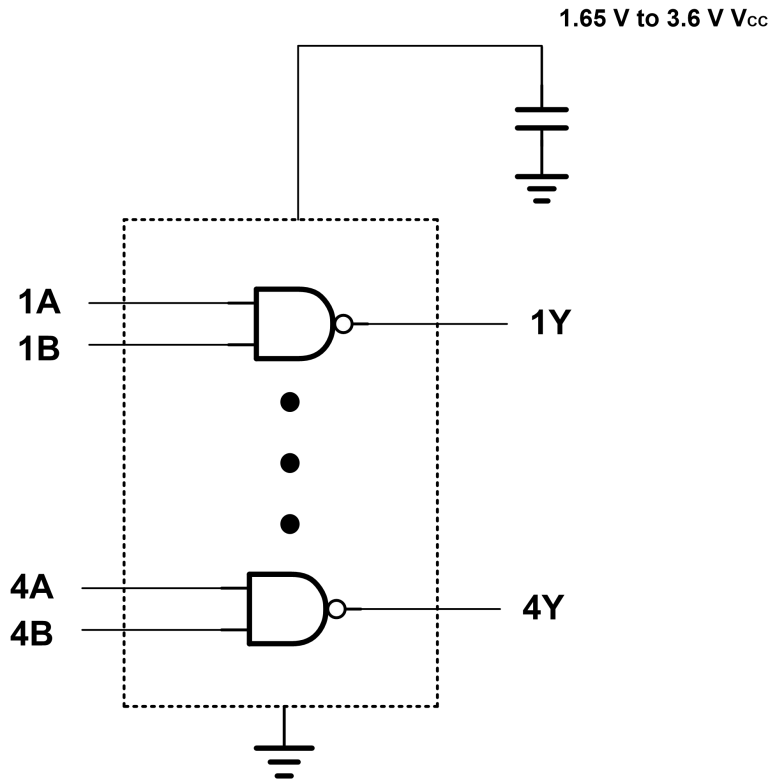
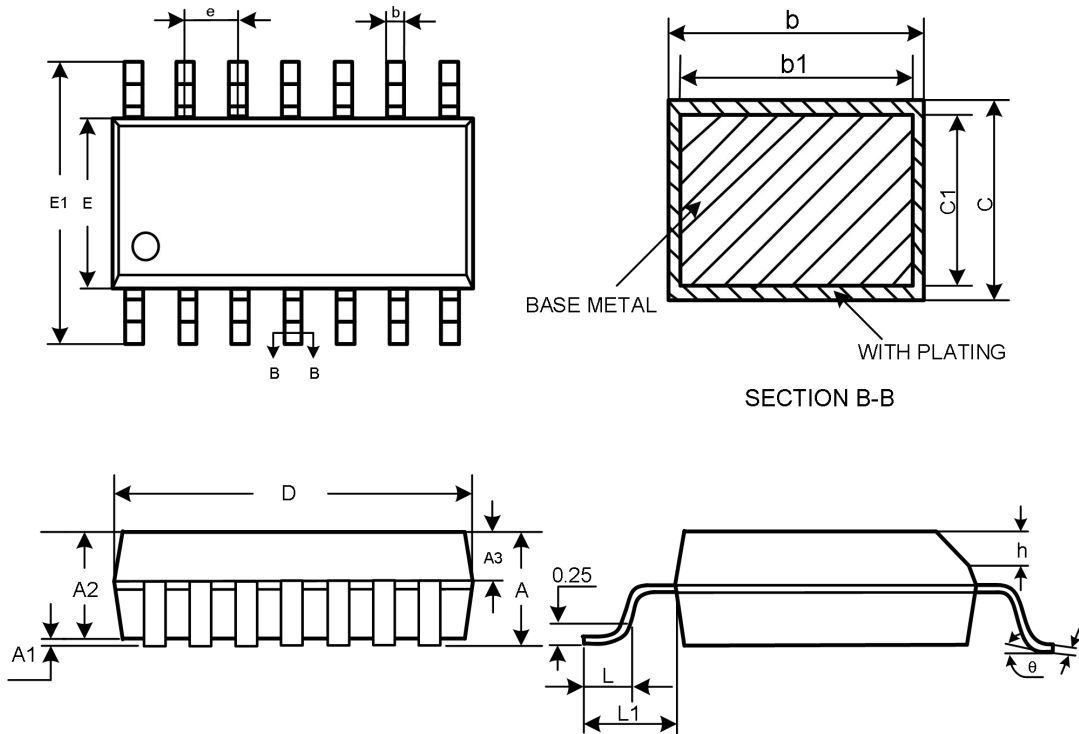


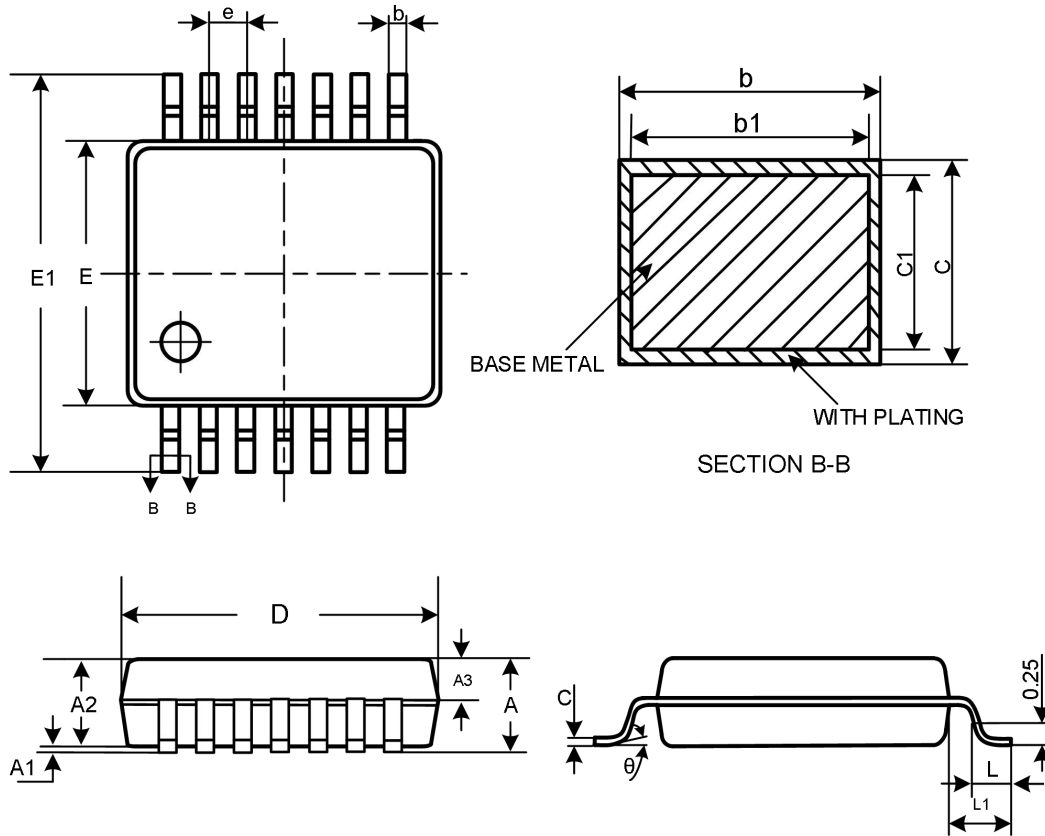
Fig.11-1. Typical Application

12 Package Outline Dimension

SOP14

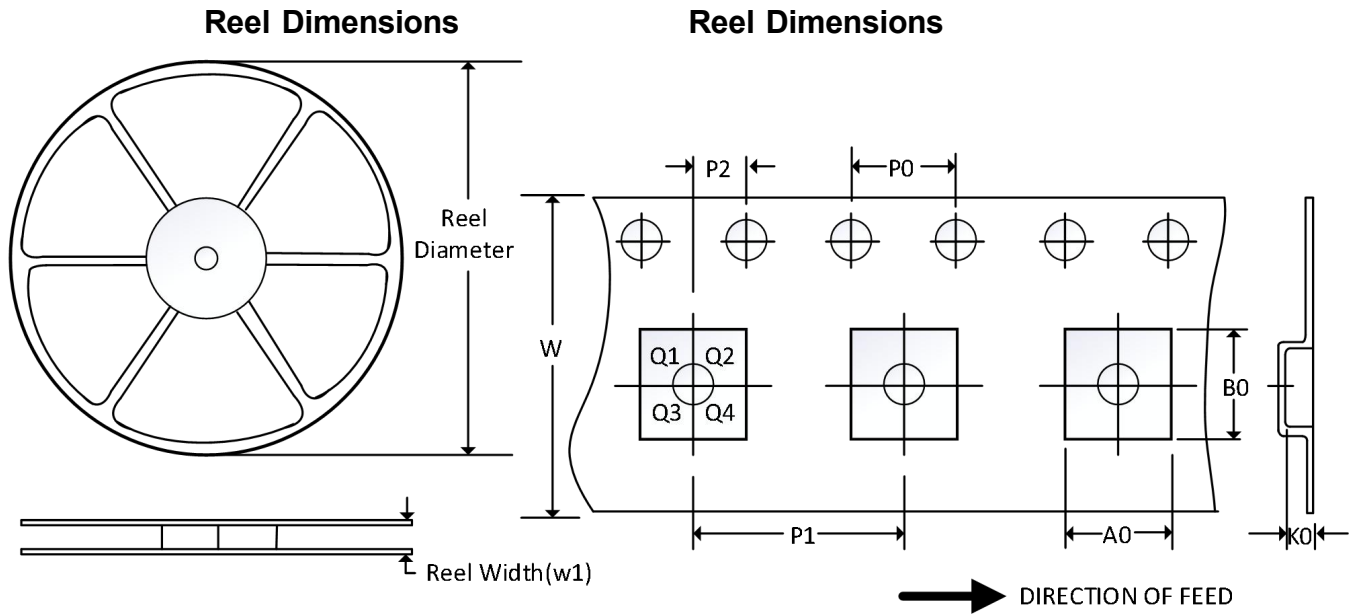


Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	—	—	1.750	—	—	0.069
A1	0.100	—	0.225	0.004	—	0.009
A2	1.300	1.400	1.500	0.051	0.055	0.059
A3	0.600	0.650	0.700	0.024	0.026	0.028
b	0.390	—	0.470	0.015	—	0.019
b1	0.380	0.410	0.440	0.015	0.016	0.017
c	0.200	—	0.240	0.008	—	0.009
c1	0.190	0.200	0.210	0.007	0.008	0.008
D	8.550	8.650	8.750	0.337	0.341	0.344
E	5.800	6.000	6.200	0.228	0.236	0.244
E1	3.800	3.900	4.000	0.150	0.154	0.157
e	1.270BSC			0.05BSC		
h	0.250	—	0.500	0.010	—	0.020
L	0.500	—	0.800	0.020	—	0.031
L1	1.050REF			0.041REF		
θ	0°	—	8°	0°	—	8°

12 Package Outline Dimension(continued)
TSSOP14


Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	—	—	1.200	—	—	0.047
A1	0.050	—	0.150	0.002	—	0.006
A2	0.900	1.000	1.050	0.035	0.039	0.041
A3	0.390	0.440	0.490	0.015	0.017	0.019
b	0.200	—	0.280	0.008	—	0.011
b1	0.190	0.220	0.250	0.007	0.009	0.010
c	0.130	—	0.170	0.005	—	0.007
c1	0.120	0.130	0.140	0.005	0.005	0.006
D	4.900	5.000	5.100	0.193	0.197	0.201
E1	4.300	4.400	4.500	0.169	0.173	0.177
E	6.200	6.400	6.600	0.244	0.252	0.260
e	0.650BSC			0.026BSC		
L	0.450	0.600	0.750	0.018	0.024	0.030
L1	1.000BCS			0.039BSC		
θ	0°	—	8°	0°	—	8°

13 Tape and Reel Information



NOTE: The picture is only for reference. Please make the object as the standard.

Key Parameter List of Tape and Reel

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-14	13"	12.4	6.95	5.60	1.20	4.0	8.0	2.0	12.0	Q1
SOIC-14 (SOP14)	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.